

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.00678	100.0	0.13479
			<b>Subtotal</b>	<b>0.00678</b>	<b>100</b>	<b>0.13479</b>
Die	Doped silicon	Silicon (Si)	7440-21-3	0.01006	100.0	0.2
	Doped silicon	Silicon (Si)	7440-21-3	0.03421	100.0	0.68
	Doped silicon	Silicon (Si)	7440-21-3	0.32201	100.0	6.4
			<b>Subtotal</b>	<b>0.36628</b>	<b>300</b>	<b>7.28</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.16538	100.0	3.2869
			<b>Subtotal</b>	<b>0.16538</b>	<b>100</b>	<b>3.2869</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02068	0.03	0.41106
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.02068	0.03	0.41106
	Copper alloy	Iron (Fe)	7439-89-6	0.06894	0.1	1.3702
	Copper alloy	Copper (Cu)	7440-50-8	68.83052	99.84	1,368.00768
			<b>Subtotal</b>	<b>68.94082</b>	<b>100</b>	<b>NaN</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.15763	4.0	23.008
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.34113	15.0	86.28
	Filler	Silica fused	60676-86-0	21.41623	74.0	425.648
	Flame retardant	Metal hydroxide		2.02586	7.0	40.264
			<b>Subtotal</b>	<b>28.94085</b>	<b>100</b>	<b>575.2</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.38868	100.0	27.6
			<b>Subtotal</b>	<b>1.38868</b>	<b>100</b>	<b>27.6</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00382	2.0	0.076
	Lead alloy	Silver (Ag)	7440-22-4	0.00478	2.5	0.095
	Lead alloy	Lead (Pb)	7439-92-1	0.18259	95.5	3.629
	Dicyandiamide	Dicyandiamide (generic)	461-58-5	0	0.5	0
	Phenolic resin	Phenolic resin		0	2.5	0
	Epoxy resin	Epoxy resin system		0	20.0	0
	Lead alloy	Silver (Ag)	7440-22-4	0	77.0	0
			<b>Subtotal</b>	<b>0.19119</b>	<b>200</b>	<b>3.8</b>
			<b>Total</b>	<b>99.99998</b>	<b>100</b>	<b>NaN</b>

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